

ABSTRACT OF THE DISCLOSURE

A semiconductor device including a semiconductor chip having first and second principal surfaces is disclosed. The semiconductor chip includes a first electrode formed on the first principal surface and a second electrode formed on the second principal surface. A first lead frame includes a first connecting portion connected to the first electrode and a first terminal portion. A second lead frame includes a second connecting portion connected to the second electrode and a second terminal portion. The semiconductor chip is sealed by a housing. The housing is formed so as not to cover part of surfaces of the first and second connecting portions.